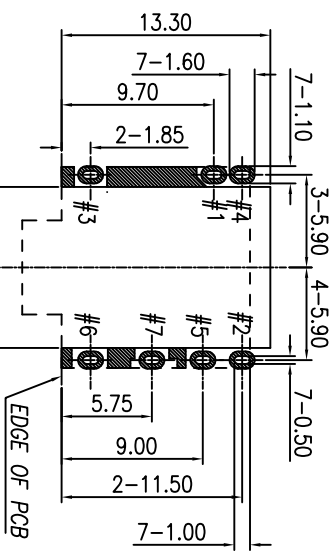
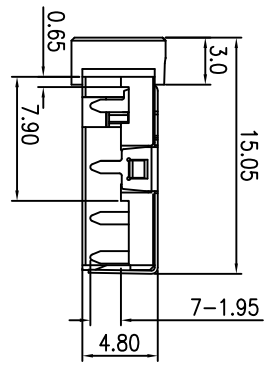
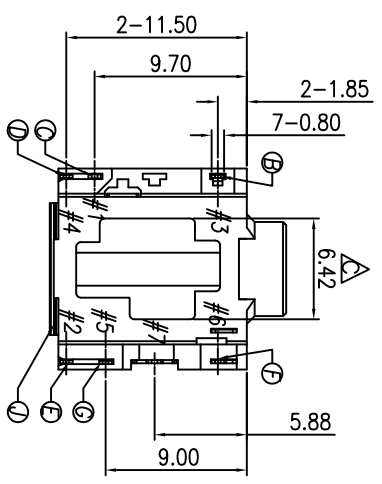
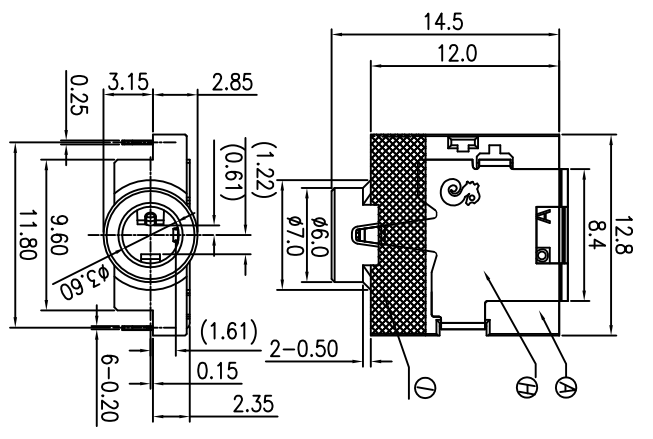
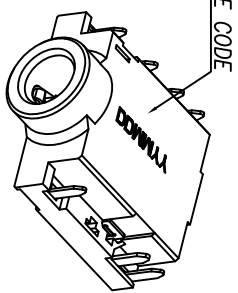
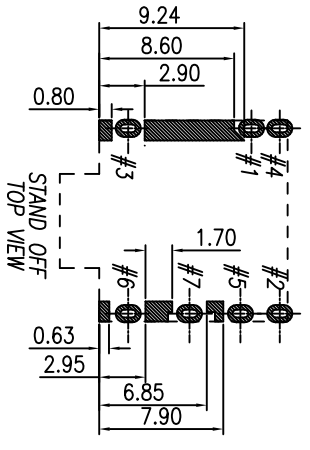
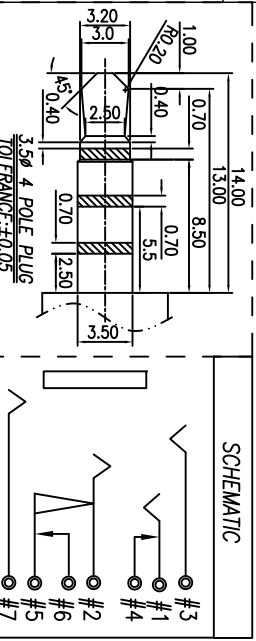


REV.	ECN NO	OR	DESCRIPTION	REVISED	DATE
C	ECN-C100360	Modify	Design	Dechao	2010/08/31
D	ECN:C110149-2	Modify	Plating Au Area	BILLY	2010/05/23
D1	ECR NO:C110349	Modify	Shield	BILLY	2010/11/03



RECOMMENDED P.C.B. LAYOUT T=1.00
TOP VIEW (TOLERANCE: ±0.05)



DECIMALS:	ANGLES:
X : ±0.5	X : ±2°
X.X : ±0.3	X.X : ±1'
X.XX : ±0.2	

- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:
 - RATING: 36V AC, 1A DC.
 - CONTACT RESISTANCE: 50m Ω MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100M Ω MIN. MEASURED BY 500 VDC.
 - MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 0.4~3.0 KGf
 - WITHDRAWAL FORCE : 0.3~2.0 KGf
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SJ2285 SERIES SPEC".
 - TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK. ○
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING.
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING:TAPE&REEL.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
J	MYLAR	1	MYLAR 0.075T	
I	MYLAR	1	MYLAR 0.075T	
H	SHIELD	1	COPPER ALLOY 0.20T	NI PLATING
G	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	△ Gold Flash on contact area and Solder fill all over Nickel Plating
F	BREAK TERMINAL	1	COPPER ALLOY 0.20T	GOLD FLASH
E	RING	1	COPPER ALLOY 0.20T	△ Gold Flash on contact area and Solder fill all over Nickel Plating
D	TIP	1	COPPER ALLOY 0.25T	
C	SHUNT	1	COPPER ALLOY 0.20T	GOLD FLASH
B	EARTH	1	COPPER ALLOY 0.20T	GOLD FLASH
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

TITLE	PART NO.	UNLESS OTHERWISE SPECIFIED TOLERANCES
350 4 POLE JACK	2SJ2284-102392	
Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DWN	Rev 2012/01/13	
CHKD	2012/01/13	
APVD	Rev 2012/01/13	
SCALE 3:1 UNIT: mm SIZE: A3 SHEET: 10F1 REV: E CUSTOMER COPY		